

Inventor Name Search Result

Your Search was:

Last Name = BANG

First Name = WON

Application#	Patent#	Status	Date Filed	Title	Inventor Name 26
60195900	Not Issued	159	04/10/2000	CONCENTRATION PROFILE ON DEMAND GAS DELIVERY SYSTEM (INDIVIDUAL DIVERT LIQUID DELIVERY SYSTEM)	BANG, WON
60106531	Not Issued	159	10/31/1998	CORROSION RESISTANT COATING	BANG, WON
10618187	Not Issued	020	07/10/2003	IN SITU SUBSTRATE HOLDER LEVELING METHOD AND APPARATUS	BANG, WON
10428967	Not Issued	020	05/01/2003	LIFT PIN ASSEMBLY FOR SUBSTRATE PROCESSING	BANG, WON B.
10374571	Not Issued	030	02/24/2003	IN-SITU HEALTH CHECK OF LIQUID INJECTION VAPORIZER	BANG, WON B.
10314401	Not Issued	071	12/09/2002	AIR PUMPING TYPE FIXED QUANTITY DISPENSING CONTAINER	BANG, WON-SEO
10222398	Not Issued	030	08/15/2002	CLOG-RESISTANT GAS DELIVERY SYSTEM	BANG, WON
10131001	6629559	150	04/24/2002	MOLDS FOR CASTING WITH CUSTOMIZED INTERNAL STRUCTURE TO COLLAPSE UPON COOLING AND TO FACILITATE CONTROL OF HEAT TRANSFER	BANG, WON B.
10081312	Not Issued	030	02/21/2002	IMPROVED CORROSION RESISTANT COATING	BANG, WON
09902283	Not Issued	061	07/10/2001	CLOG RESISTANT INJECTION VALVE	BANG, WON
09832168	Not Issued	123	04/10/2001	CONCENTRATION PROFILE ON DEMAND GAS DELIVERY SYSTEM (INDIVIDUAL DIVERT DELIVERY SYSTEM)	BANG, WON
09637839	6346481	150	08/12/2000	METHOD OF REDUCING PITTING OF A COATED HEATER	BANG, WON
09620630	Not Issued	161	07/20/2000	DEPOSITION RESISTANT LINING FOR CVD CHAMBER	BANG, WON B.
09577920	6397922	150	05/24/2000	MOLDS FOR CASTING WITH CUSTOMIZED INTERNAL STRUCTURE TO COLLAPSE UPON COOLING AND TO FACILITATE	BANG, WON B.

CONTROL OF HEAT TRANSFER					
09565323	Not Issued	161	05/05/2000	METHOD FOR MAKING PURCHASES USING AN INTERMEDIARY	BANG, WONG SHIH
09428140	6379492	150	10/26/1999	CORROSION RESISTANT COATING	BANG , WON
09427777	Not Issued	160	10/26/1999	CORROSION RESISTANT COATING	BANG , WON
09248789	6267820	150	02/12/1999	CLOG RESISTANT INJECTION VALVE	BANG , WON
09163282	6261374	150	09/29/1998	CLOG RESISTANT GAS DELIVERY SYSTEM	BANG , WON
09144722	5948958	150	09/01/1998	METHOD AND APPARATUS FOR VERIFYING THE CALIBRATION OF SEMICONDUCTOR PROCESSING EQUIPMENT	BANG , WON
09105970	6235120	150	06/26/1998	COATING FOR PARTS USED IN SEMICONDUCTOR PROCESSING CHAMBERS	BANG , WON
09047284	6117244	150	03/24/1998	DEPOSITION RESISTANT LINING FOR CVD CHAMBER	BANG, WON B.
09009907	6063198	150	01/21/1998	HIGH PRESSURE RELEASE DEVICE FOR SEMICONDUCTOR FABRICATING EQUIPMENT	BANG , WON
08954299	6090206	150	10/20/1997	THROTTLE VALVE PROVIDING ENHANCED CLEANING	BANG, WON B.
08953444	6110556	150	10/17/1997	LID ASSEMBLY FOR A PROCESS CHAMBER EMPLOYING ASYMMETRIC FLOW GEOMETRIES	BANG , WON
08332780	5591766	150	11/01/1994	SOLID ORAL FORMULATIONS OF PYRIDONE CARBOXYLIC ACIDS	BANG , WON Y.

Inventor Search Completed: No Records to Display.

Search Another: Inventor	Last Name	First Name
	<input type="text" value="BANG"/>	<input type="text" value="WON"/>
		<input type="button" value="Search"/>

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | [Home page](#)

Inventor Name Search Result

Your Search was:

Last Name = CHEN

First Name = CHEN-AN

Application#	Patent#	Status	Date Filed	Title	Inventor Name 44
60513310	Not Issued	020	10/21/2003	PLATING SYSTEM WITH INTEGRATED SUBSTRATE INSPECTION	CHEN, CHEN-AN
60352191	Not Issued	159	01/26/2002	APPARATUS AND METHOD OF GENERATION OF A PLASMA IN DEPOSITION PROCESSES	CHEN, CHEN-AN
60287280	Not Issued	159	04/28/2001	CHEMICAL VAPOR DEPOSITION CHAMBER	CHEN, CHEN-AN
60106531	Not Issued	159	10/31/1998	CORROSION RESISTANT COATING	CHEN , CHEN-AN
10621042	Not Issued	030	07/15/2003	METHOD AND APPARATUS FOR FLUID FLOW CONTROL	CHEN, CHEN-AN
10453227	Not Issued	030	06/02/2003	METHOD AND APPARATUS FOR PROCESSING SEMICONDUCTOR SUBSTRATES WITH HYDROXYL RADICALS	CHEN, CHEN-AN
10373749	Not Issued	041	02/27/2003	KEY RING WITH A DIAMOND-SHINING ORNAMENTAL BLOCK	CHENG, CHEN-AN
10339390	Not Issued	030	01/10/2003	ELASTIC FLASH STICK WITH AN ORNAMENTAL BLOCK	CHENG, CHEN-AN
10302240	Not Issued	041	11/22/2002	CVD PLASMA ASSISTED LOWER DIELECTRIC CONSTANT SICOH FILM	CHEN, CHEN-AN
10219307	6513167	150	08/16/2002	HEADBAND ASSEMBLY	CHENG, CHEN-AN
10197940	Not Issued	030	07/16/2002	APPARATUS AND METHOD FOR PLASMA ASSISTED DEPOSITION	CHEN, CHEN-AN
10173408	6641262	150	06/18/2002	EYEGLASSES WITH DIAMOND-SHINING EFFECT	CHENG, CHEN-AN
10134206	Not Issued	041	04/26/2002	CHEMICAL VAPOR DEPOSITION CHAMBER	CHEN, CHEN-AN
10131402	6626184	150	04/25/2002	OPEN-LOOP HEADBAND ASSEMBLY WITH A FLICKERING DECORATION LIGHT DEVICE	CHENG, CHEN-AN
10122481	Not Issued	030	04/12/2002	METHOD FOR CLEANING A PROCESS CHAMBER	CHEN, CHEN-AN
10100148	Not Issued	041	03/19/2002	ORNAMENTAL COMB ASSEMBLY	CHENG, CHEN-AN

10081312	Not Issued	030	02/21/2002	IMPROVED CORROSION RESISTANT COATING	CHEN, CHEN-AN
09902283	Not Issued	061	07/10/2001	CLOG RESISTANT INJECTION VALVE	CHEN, CHEN-AN
09900900	6546562	150	07/10/2001	ADJUSTABLE ENCIRCLING HEADBAND	CHENG, CHEN-AN
09900898	Not Issued	161	07/10/2001	CAP STRUCTURE OF A CONTAINER	CHENG, CHEN-AN
09900857	6382218	150	07/10/2001	OPEN-LOOP HEADBAND ASSEMBLY	CHENG, CHEN-AN
09895104	6591850	150	06/29/2001	METHOD AND APPARATUS FOR FLUID FLOW CONTROL	CHEN, CHEN-AN
09885985	6486082	150	06/18/2001	CVD PLASMA ASSISTED LOWER DIELECTRIC CONSTANT SICOH FILM	CHEN, CHEN-AN
09882769	6506994	150	06/15/2001	LOW PROFILE THICK FILM HEATERS IN MULTI-SLOT BAKE CHAMBER	CHEN, CHEN-AN
09820586	Not Issued	094	03/28/2001	PURGE HEATER DESIGN AND PROCESS DEVELOPMENT FOR THE IMPROVEMENT OF LOW K FILM PROPERTIES	CHEN, CHEN-AN
09769475	6398019	150	01/26/2001	CUP WITH INDICATING DEVICE FOR CELLULAR PHONE CALL	CHENG, CHEN-AN
09696034	6288498	150	10/26/2000	STRUCTURE OF FLICKERING DECORATION LIGHT	CHENG, CHEN-AN
09637839	6346481	150	08/12/2000	METHOD OF REDUCING PITTING OF A COATED HEATER	CHEN, CHEN-AN
09561325	6387207	150	04/28/2000	INTEGRATION OF REMOTE PLASMA GENERATOR WITH SEMICONDUCTOR PROCESSING CHAMBER	CHEN, CHEN-AN
09557079	6596343	150	04/21/2000	METHOD FOR PROCESSING SEMICONDUCTOR SUBSTRATES WITH HYDROXYL RADICALS	CHEN, CHEN-AN
09550448	6303501	150	04/17/2000	GAS MIXING APPARATUS AND METHOD	CHEN, CHEN-AN
09428140	6379492	150	10/26/1999	CORROSION RESISTANT COATING	CHEN, CHEN-AN
09427777	Not Issued	160	10/26/1999	CORROSION RESISTANT COATING	CHEN, CHEN-AN
09342667	6358327	150	06/29/1999	METHOD FOR ENDPOINT DETECTION USING THROTTLE VALVE POSITION	CHEN, CHEN-AN
09290228	6004055	250	04/13/1999	NAIL ENAMEL CONTAINER	CHENG, CHEN-AN
09248789	6267820	150	02/12/1999	CLOG RESISTANT INJECTION VALVE	CHEN, CHEN-AN
09163282	6261374	150	09/29/1998	CLOG RESISTANT GAS DELIVERY SYSTEM	CHEN, CHEN-AN

<u>09144722</u>	<u>5948958</u>	150	09/01/1998	METHOD AND APPARATUS FOR VERIFYING THE CALIBRATION OF SEMICONDUCTOR PROCESSING EQUIPMENT	CHEN , CHEN-AN
<u>09105970</u>	<u>6235120</u>	150	06/26/1998	COATING FOR PARTS USED IN SEMICONDUCTOR PROCESSING CHAMBERS	CHEN , CHEN-AN
<u>09004820</u>	<u>6110284</u>	150	01/09/1998	APPARATUS AND A METHOD FOR SHIELDING LIGHT EMANATING FROM A LIGHT SOURCE HEATING A SEMICONDUTOR PROCESSING CHAMBER	CHEN , CHEN-AN
<u>08893414</u>	<u>6068703</u>	150	07/11/1997	GAS MIXING APPARATUS AND METHOD	CHEN , CHEN-AN
<u>08890805</u>	<u>6024799</u>	150	07/11/1997	CHEMICAL VAPOR DEPOSITION MANIFOLD	CHEN , CHEN-AN
<u>08755219</u>	Not Issued	168	11/22/1996	HIGH TEMPERATURE RESISTIVE HEATER	CHEN , CHEN-AN
<u>08717780</u>	<u>6066836</u>	150	09/23/1996	HIGH TEMPERATURE RESISTIVE HEATER FOR A PROCESS CHAMBER	CHEN , CHEN-AN

Inventor Search Completed: No Records to Display.

Search Another: Inventor

Last Name

First Name

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | [Home page](#)

Inventor Name Search Result

Your Search was:

Last Name = VENKATARAMAN

First Name = SHANKAR

Application#	Patent#	Status	Date Filed	Title	Inventor Name 35
60143091	Not Issued	159	07/09/1999	APPARATUS FOR DISTRIBUTING GASES IN A CHEMICAL VAPOR DEPOSITION SYSTEM	VENKATARAMAN , SHANKAR
10621042	Not Issued	030	07/15/2003	METHOD AND APPARATUS FOR FLUID FLOW CONTROL	VENKATARAMAN, SHANKAR
10449260	Not Issued	020	05/30/2003	METHOD AND SYSTEM FOR TRANSPORTING FAULTS ACROSS A NETWORK	VENKATARAMAN, SHANKAR
10383837	Not Issued	071	03/07/2003	METHOD OF IMPROVING INTERLAYER ADHESION	VENKATARAMAN, SHANKAR
10375853	Not Issued	041	02/25/2003	METHOD OF DEPOSITING LOW DIELECTRIC CONSTANT SILICON CARBIDE LAYERS	VENKATARAMAN, SHANKAR
10375793	Not Issued	030	02/25/2003	METHOD OF DEPOSITING LOW DIELECTRIC CONSTANT SILICON CARBIDE LAYERS	VENKATARAMAN, SHANKAR
10365061	Not Issued	030	02/12/2003	EFFICIENT FRAMING PROCEDURE FOR VARIABLE LENGTH PACKETS	VENKATARAMAN, SHANKAR
10354214	Not Issued	030	01/27/2003	METHOD AND APPARATUS FOR CLEANING A CVD CHAMBER	VENKATARAMAN, SHANKAR
10346836	Not Issued	030	01/16/2003	CLEANING OF CVD CHAMBERS USING REMOTE SOURCE WITH CXFYOZ BASED CHEMISTRY	VENKATARAMAN, SHANKAR
10327209	Not Issued	030	12/20/2002	BLOCKER PLATE BYPASS DESIGN TO IMPROVE CLEAN RATE AT THE EDGE OF THE CHAMBER	VENKATARAMAN, SHANKAR
10302350	Not Issued	030	11/22/2002	METHOD FOR CLEANING PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION CHAMBER USING VERY HIGH FREQUENCY ENERGY	VENKATARAMAN, SHANKAR
10302240	Not Issued	041	11/22/2002	CVD PLASMA ASSISTED LOWER DIELECTRIC CONSTANT SICOH FILM	VENKATARAMAN, SHANKAR
10279367	Not Issued	093	10/23/2002	PLASMA ENHANCED CVD LOW K CARBON-DOPED SILICON OXIDE FILM DEPOSITION USING VHF-RF POWER	VENKATARAMAN, SHANKAR

10245443	Not Issued	041	09/16/2002	HEATED GAS DISTRIBUTION PLATE FOR A PROCESSING CHAMBER	VENKATARAMAN, SHANKAR
10245442	Not Issued	030	09/16/2002	METHODS FOR OPERATING A CHEMICAL VAPOR DEPOSITION CHAMBER USING A HEATED GAS DISTRIBUTION PLATE	VENKATARAMAN, SHANKAR
10196498	Not Issued	030	07/15/2002	METHOD OF DEPOSITING DIELECTRIC MATERIALS IN DAMASCENE APPLICATIONS	VENKATARAMAN, SHANKAR
10183566	Not Issued	030	06/28/2002	NEEDLE CONTROLLED FUEL INJECTOR WITH TWO CONTROL VALVES	VENKATARAMAN, SHANKAR C.
10122481	Not Issued	030	04/12/2002	METHOD FOR CLEANING A PROCESS CHAMBER	VENKATARAMAN, SHANKAR
10115665	Not Issued	030	04/03/2002	ACCELERATED PLASMA CLEAN	VENKATARAMAN, SHANKAR
10081312	Not Issued	030	02/21/2002	IMPROVED CORROSION RESISTANT COATING	VENKATARAMAN, SHANKAR
09942328	Not Issued	041	08/28/2001	STREAMLINED CACHE COHERENCY PROTOCOL SYSTEM AND METHOD FOR A MULTIPLE PROCESSOR SINGLE CHIP DEVICE	VENKATARAMAN, SHANKAR
09916598	Not Issued	041	07/26/2001	CACHE COHERENT SPLIT TRANSACTION MEMORY BUS ARCHITECTURE AND PROTOCOL FOR A MULTI PROCESSOR CHIP DEVICE	VENKATARAMAN, SHANKAR
09895104	6591850	150	06/29/2001	METHOD AND APPARATUS FOR FLUID FLOW CONTROL	VENKATARAMAN, SHANKAR
09885985	6486082	150	06/18/2001	CVD PLASMA ASSISTED LOWER DIELECTRIC CONSTANT SICOH FILM	VENKATARAMAN, SHANKAR
09865605	Not Issued	030	05/29/2001	CHIP MULTIPROCESSOR WITH MULTIPLE OPERATING SYSTEMS	VENKATARAMAN, SHANKAR
09820586	Not Issued	094	03/28/2001	PURGE HEATER DESIGN AND PROCESS DEVELOPMENT FOR THE IMPROVEMENT OF LOW K FILM PROPERTIES	VENKATARAMAN, SHANKAR
09793818	6537733	150	02/23/2001	METHOD OF DEPOSITING LOW DIELECTRIC CONSTANT SILICON CARBIDE LAYERS	VENKATARAMAN, SHANKAR
09657392	Not Issued	071	09/08/2000	DUAL PLASMA TREATMENT OF SILICON CARBIDE FILMS	VENKATARAMAN, SHANKAR
09633078	Not Issued	161	08/04/2000	METHOD AND APPARATUS FOR REMOVING SILICON CARBIDE FROM SEMICONDUCTOR SUBSTRATES	VENKATARAMAN, SHANKAR
09609994	6495233	150	07/05/2000	APPARATUS FOR DISTRIBUTING	VENKATARAMAN,

				GASES IN A CHEMICAL VAPOR DEPOSITION SYSTEM	SHANKAR
09561325	6387207	150	04/28/2000	INTEGRATION OF REMOTE PLASMA GENERATOR WITH SEMICONDUCTOR PROCESSING CHAMBER	VENKATARAMAN, SHANKAR
09428140	6379492	150	10/26/1999	CORROSION RESISTANT COATING	VENKATARAMAN , SHANKAR
09338470	6413583	150	06/22/1999	FORMATION OF A LIQUID-LIKE SILICA LAYER BY REACTION OF AN ORGANOSILICON COMPOUND AND A HYDROXYL FORMING COMPOUND	VENKATARAMAN , SHANKAR
09246036	6374831	150	02/04/1999	ACCELERATED PLASMA CLEAN	VENKATARAMAN , SHANKAR
08865505	Not Issued	161	05/30/1997	METHOD AND SYSTEM FOR RECORDING AND REPRODUCING INFORMATION	VENKATARAMAN , SHANKAR

Inventor Search Completed: No Records to Display.

Search Another: Inventor	Last Name	First Name
	VENKATARAMAN	SHANKAR
		<input type="button" value="Search"/>

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | [Home page](#)

Inventor Name Search Result

Your Search was:

Last Name = BHATNAGAR

First Name = AJAY

Application#	Patent#	Status	Date Filed	Title	Inventor Name 8
60425482	Not Issued	020	11/12/2002	ORGANIC COMPOUNDS	BHATNAGAR, AJAY S.
60294094	Not Issued	159	05/29/2001	METHOD AND SYSTEM FOR LOGGING INTO AND PROVIDING ACCESS TO A COMPUTER SYSTEM VIA A COMMUNICATIONS NETWORK	BHATNAGAR, AJAY
10081312	Not Issued	030	02/21/2002	IMPROVED CORROSION RESISTANT COATING	BHATNAGAR, AJAY
09428140	6379492	150	10/26/1999	CORROSION RESISTANT COATING	BHATNAGAR , AJAY
08300668	5583128	150	09/02/1994	CONTRACEPTION IN FEMALE PRIMATES WITHOUT AFFECTING THE MENSTRUAL CYCLE	BHATNAGAR , AJAY
08195892	Not Issued	164	02/10/1994	CONTRACEPTION IN FEMALE PRIMATES WITHOUT AFFECTING THE MENSTRUAL CYCLE	BHATNAGAR , AJAY
07872272	Not Issued	166	04/22/1992	CONTRACEPTION IN FEMALE PRIMATES WITHOUT AFFECTING THE MENSTRUAL CYCLE	BHATNAGAR , AJAY
07412369	5057521	150	09/26/1989	USE OF BICYCLIC IMIDAZOLE COMPOUNDS FOR THE TREATMENT OF HYPERALDOSTERONISM	BHATNAGAR , AJAY

Inventor Search Completed: No Records to Display.

Search Another: Inventor	Last Name <input type="text" value="BHATNAGAR"/>	First Name <input type="text" value="AJAY"/>	<input type="button" value="Search"/>
--------------------------	---	---	---------------------------------------

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | Home page

L Number	Hits	Search Text	DB	Time stamp
1	2	6346481.pn. or 6235120.pn.	USPAT; US-PGPUB	2004/01/29 09:32
2	3	(Bang.in. or Chen.in. or Venkataraman.in. or Bhatnagar.in. or (Applied adj Material).as.) and ((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same (density) same (purity)	USPAT; US-PGPUB	2004/01/29 10:01
3	3	(Bang.in. or Chen.in. or Venkataraman.in. or Bhatnagar.in. or (Applied adj Material).as.) and ((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride))) same (density) same (purity)	USPAT; US-PGPUB	2004/01/29 09:46
4	0	((Bang.in. or Chen.in. or Venkataraman.in. or Bhatnagar.in. or (Applied adj Material).as.) and ((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride))) same (density) same (purity)) not ((Bang.in. or Chen.in. or Venkataraman.in. or Bhatnagar.in. or (Applied adj Material).as.) and ((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same (density) same (purity))	USPAT; US-PGPUB	2004/01/29 09:37
5	17	(Bang.in. or Chen.in. or Venkataraman.in. or Bhatnagar.in. or (Applied adj Material).as.) and ((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same ((corros\$3 or corrode\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$3) with (fluorine or NF3 or "NF.sub.3" or CHF3 or "CHF.sub.3" or heater or aluminum or Al or AlN or (aluminum adj nitride) or support or pedestal or susceptor))	USPAT; US-PGPUB	2004/01/29 10:50
6	14	((Bang.in. or Chen.in. or Venkataraman.in. or Bhatnagar.in. or (Applied adj Material).as.) and ((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same ((corros\$3 or corrode\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$3) with (fluorine or NF3 or "NF.sub.3" or CHF3 or "CHF.sub.3" or heater or aluminum or Al or AlN or (aluminum adj nitride) or support or pedestal or susceptor)) not ((Bang.in. or Chen.in. or Venkataraman.in. or Bhatnagar.in. or (Applied adj Material).as.) and ((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride))) same (density) same (purity))	USPAT; US-PGPUB	2004/01/29 09:41
7	1	(Bang or Chen or Venkataraman or Bhatnagar or (Applied adj Material)) and ((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride))) same (density) same (purity)	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 09:47

8	5	(Bang or Chen or Venkataraman or Bhatnagar or (Applied adj Material)) and ((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) and ((corros\$3 or corrod\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$3) with (fluorine or NF3 or "NF.sub.3" or CHF3 or "CHF.sub.3" or heater or aluminum or Al or AlN or (aluminum adj nitride) or support or pedestal or susceptor))	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 09:48
9	5	((Bang or Chen or Venkataraman or Bhatnagar or (Applied adj Material)) and ((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) and ((corros\$3 or corrod\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$3) with (fluorine or NF3 or "NF.sub.3" or CHF3 or "CHF.sub.3" or heater or aluminum or Al or AlN or (aluminum adj nitride) or support or pedestal or susceptor)) not ((Bang or Chen or Venkataraman or Bhatnagar or (Applied adj Material)) and ((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)))) same (density) same (purity))	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 09:59
10	1924	(427/585,593,596,255.28,255.39).CCLS.	USPAT; US-PGPUB	2004/01/29 09:59
11	1918	(427/372.2,383.1).CCLS.	USPAT; US-PGPUB	2004/01/29 10:00
12	548	(423/490,497).CCLS.	USPAT; US-PGPUB	2004/01/29 10:00
13	4257	(118/715,725,728).CCLS.	USPAT; US-PGPUB	2004/01/29 10:00
14	8487	((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.)	USPAT; US-PGPUB	2004/01/29 10:00
15	0	((423/490,497).CCLS.) and ((427/585,593,596,255.28,255.39).CCLS.) or ((427/372.2,383.1).CCLS.) or ((118/715,725,728).CCLS.))	USPAT; US-PGPUB	2004/01/29 10:00
16	3	(((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.)) and ((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same (density or dense) same (purity or pure or impure or impurit\$3)	USPAT; US-PGPUB	2004/01/29 13:08
17	1	6162495.bn.	USPAT; US-PGPUB	2004/01/29 10:03
18	31	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same (density or dense) same (purity or pure or impure or impurit\$3)	USPAT; US-PGPUB	2004/01/29 10:08

19	28	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same (density or dense) same (purity or pure or impure or impurit\$3)) not (((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.)) and ((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same (density or dense) same (purity or pure or impure or impurit\$3))	USPAT; US-PGPUB	2004/01/29 10:04
20	23	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with (density or dense)) and (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with (purity or pure or impure or impurit\$3))	USPAT; US-PGPUB	2004/01/29 12:44
21	9	(((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with (density or dense)) and (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with (purity or pure or impure or impurit\$3)) not (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same (density or dense) same (purity or pure or impure or impurit\$3))	USPAT; US-PGPUB	2004/01/29 10:09
22	38	(((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (density or dense)) and (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (purity or pure or impure or impurit\$3))) with (purity or pure or impure or impurit\$3))	USPAT; US-PGPUB	2004/01/29 10:13

23	15	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride))) with (density or dense) and (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride))) with (purity or pure or impure or impurit\$3)) not (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same (density or dense) same (purity or pure or impure or impurit\$3)) or (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with (density or dense)) and (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with (purity or pure or impure or impurit\$3)))	USPAT; US-PGPUB	2004/01/29 10:13
24	48	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same (density or dense) and (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same (purity or pure or impure or impurit\$3))	USPAT; US-PGPUB	2004/01/29 10:31

25	8	<p>((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same (density or dense) and ((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same (purity or pure or impure or impurit\$3)) not (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same (density or dense) same (purity or pure or impure or impurit\$3)) not (((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.)) and ((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same (density or dense) same (purity or pure or impure or impurit\$3)) or (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with (density or dense)) and (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with (purity or pure or impure or impurit\$3)) or (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (density or dense)) and (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (purity or pure or impure or impurit\$3)))</p>	USPAT; US-PGPUB	2004/01/29 10:28
26	53	<p>((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or (electron adj beam))) same (density or dense) same (temperature)</p>	USPAT; US-PGPUB	2004/01/29 11:28
27	77	<p>((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) same (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or (electron adj beam))) same (density or dense) same (temperature or temp\$8))</p>	USPAT; US-PGPUB	2004/01/29 12:10

28	24	((MgF ₂ or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) same (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or (electron adj beam))) same (density or dense) same (temperature or temp\$8)) not (((MgF ₂ or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or (electron adj beam))) same (density or dense) same (temperature)))	USPAT; US-PGPUB	2004/01/29 10:39
29	386	((MgF ₂ or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or (electron adj beam))) and ((density or dense) with (temperature or temp\$8))	USPAT; US-PGPUB	2004/01/29 11:29
30	161	((MgF ₂ or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or (electron adj beam))) and ((density or dense) with (temperature or temp\$8) with (coat\$3 or film or layer or deposit\$3 or apply\$3 or \$4CVD or EB or (electron adj beam))))	USPAT; US-PGPUB	2004/01/29 10:42
31	11	((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.) and ((MgF ₂ or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same ((corros\$3 or corrod\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$3) with (fluorine or NF ₃ or "NF.sub.3" or CHF ₃ or "CHF.sub.3" or heater or aluminum or Al or AlN or (aluminum adj nitride) or support or pedestal or susceptor))	USPAT; US-PGPUB	2004/01/29 10:54
32	306	((MgF ₂ or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same ((corros\$3 or corrod\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$3) with (fluorine or NF ₃ or "NF.sub.3" or CHF ₃ or "CHF.sub.3" or heater or aluminum or Al or AlN or (aluminum adj nitride) or support or pedestal or susceptor))	USPAT; US-PGPUB	2004/01/29 11:30

33	295	((MgF ₂ or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same ((corros\$3 or corrod\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$3) with (fluorine or NF ₃ or "NF.sub.3" or CHF ₃ or "CHF.sub.3" or heater or aluminum or Al or AlN or (aluminum adj nitride) or support or pedestal or susceptor)) not (((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.)) and ((MgF ₂ or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same ((corros\$3 or corrod\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$3) with (fluorine or NF ₃ or "NF.sub.3" or CHF ₃ or "CHF.sub.3" or heater or aluminum or Al or AlN or (aluminum adj nitride) or support or pedestal or susceptor))	USPAT; US-PGPUB	2004/01/29 10:55
34	643	((MgF ₂ or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with ((corros\$3 or corrod\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$3)) (((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.)) and ((MgF ₂ or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with ((corros\$3 or corrod\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$4 or fluorine or NF ₃ or "NF.sub.3" or CHF ₃ or "CHF.sub.3" or heater or aluminum or Al or AlN or (aluminum adj nitride) or support or pedestal or susceptor))	USPAT; US-PGPUB	2004/01/29 11:33
35	49	(((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.)) and ((MgF ₂ or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with ((corros\$3 or corrod\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$4 or fluorine or NF ₃ or "NF.sub.3" or CHF ₃ or "CHF.sub.3" or heater or aluminum or Al or AlN or (aluminum adj nitride) or support or pedestal or susceptor))	USPAT; US-PGPUB	2004/01/29 11:08
36	0	(((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.)) and ((MgF ₂ or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) and (density or dense) and (purity or pure or impure or impurit\$3)	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 11:25
37	5	((MgF ₂ or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) and (density or dense) and (purity or pure or impure or impurit\$3) ((MgF ₂ or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride))) and (density or dense) and (purity or pure or impure or impurit\$3)	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 11:26
38	31	((MgF ₂ or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride))) and (density or dense) and (purity or pure or impure or impurit\$3)	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 11:26

39	26	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride))) and (density or dense) and (purity or pure or impure or impurit\$3)) not (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) and (density or dense) and (purity or pure or impure or impurit\$3))	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 11:26
40	7	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or (electron adj beam))) same (density or dense) same (temperature)	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 11:28
41	8	((((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or (electron adj beam))) and ((density or dense) with (temperature or temp\$8)))	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 11:29
42	4	((((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or (electron adj beam))) and ((density or dense) with (temperature or temp\$8)))) not (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or (electron adj beam))) same (density or dense) same (temperature))	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 11:29
43	78	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same ((corross\$3 or corrod\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$3) with (fluorine or NF3 or "NF.sub.3" or CHF3 or "CHF.sub.3" or heater or aluminum or Al or AlN or (aluminum adj nitride) or support or pedestal or susceptor))	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 11:30
44	245	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with ((corross\$3 or corrod\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$3))	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 11:54

45	177	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with ((corros\$3 or corrod\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$3)) not (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same ((corros\$3 or corrod\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$3) with (fluorine or NF3 or "NF.sub.3" or CHF3 or "CHF.sub.3" or heater or aluminum or Al or AlN or (aluminum adj nitride) or support or pedestal or susceptor)))	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 11:34
46	1003	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or EBPVD or (electron adj beam)) same ((corros\$3 or corrod\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$3))	USPAT; US-PGPUB	2004/01/29 12:00
47	196	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or EBPVD or (electron adj beam)) same ((corros\$3 or corrod\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$3)) and ((coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or EBPVD or (electron adj beam)) same temperature same pressure)	USPAT; US-PGPUB	2004/01/29 11:57
48	67	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or EBPVD or (electron adj beam)) same ((corros\$3 or corrod\$3 or protect\$3 or pit or pitted or pitting or defect\$3 or damag\$3)) and ((coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or EBPVD or (electron adj beam)) with temperature with pressure)	USPAT; US-PGPUB	2004/01/29 11:57
49	98	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or EBPVD or (electron adj beam)) same temperature same pressure	USPAT; US-PGPUB	2004/01/29 12:06
50	15	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or EBPVD or (electron adj beam)) same temperature same pressure	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 12:06
51	32	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3 or EB or (electron adj beam))) same (porous or porosity or nonporous or packed or packing or pack) same (temperature or temp\$8))	USPAT; US-PGPUB	2004/01/29 12:18

52	4	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride)) same (EB or (electron adj beam) or EBCVD or EBPVD)) same (porous or porosity or nonporous or packed or packing or pack or dens\$4) same (temperature or temp\$8))	USPAT; US-PGPUB	2004/01/29 12:19
53	8	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride)) same (EB or (electron adj beam) or EBCVD or EBPVD)) same (porous or porosity or nonporous or packed or packing or pack or dens\$4) same (pur\$4 or impur\$6 or contamin\$5))	USPAT; US-PGPUB	2004/01/29 12:20
54	13	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride)) same (EB or (electron adj beam) or EBCVD or EBPVD)) same temperature same pressure)	USPAT; US-PGPUB	2004/01/29 12:27
55	27	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride)) same (EB or (electron adj beam) or EBCVD or EBPVD)) and (high\$3 adj temperature) and ((low\$3 or reduc\$5 or vacuum) near2 pressure))	USPAT; US-PGPUB	2004/01/29 12:25
56	54	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride)) same (EB or (electron adj beam) or EBCVD or EBPVD) and ((substrate or deposit\$3 or EB or (electron adj beam) or EBCVD or EBPVD or coat\$3) near8 temperature) and ((chamber or reactor or vessel or deposit\$3 or EB or (electron adj beam) or EBCVD or EBPVD or coat\$3) near8 pressure))	USPAT; US-PGPUB	2004/01/29 12:59
57	42	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride)) same (EB or (electron adj beam) or EBCVD or EBPVD)) and ((substrate or deposit\$3 or EB or (electron adj beam) or EBCVD or EBPVD or coat\$3) near8 temperature) and ((chamber or reactor or vessel or deposit\$3 or EB or (electron adj beam) or EBCVD or EBPVD or coat\$3) near8 pressure)) not (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride)) same (EB or (electron adj beam) or EBCVD or EBPVD)) same temperature same pressure))	USPAT; US-PGPUB	2004/01/29 12:27
58	25	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with (density or dense or pack\$3 or void or pore or porous or nonporous) and ((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with (purity or pure or impure or impurit\$3 or contamin\$6))	USPAT; US-PGPUB	2004/01/29 12:45

59	2	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with (density or dense or pack\$3 or void or pore or porous or nonporous) and (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with (purity or pure or impure or impurit\$3 or contamin\$6)) not (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) same (density or dense) same (purity or pure or impure or impurit\$3)) or (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with (density or dense)) and (((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) with (purity or pure or impure or impurit\$3)))	USPAT; US-PGPUB	2004/01/29 12:45
60	10	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride)) with temperature with "300"))	USPAT; US-PGPUB	2004/01/29 13:00
61	87	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride)) with "300"))	USPAT; US-PGPUB	2004/01/29 13:00
62	716	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) and ((heater or susceptor or substrate or pedestal) with (polish\$4 or rough\$5 or smooth\$3 or 10RA or RA10))	USPAT; US-PGPUB	2004/01/29 13:11
63	36	((MgF2 or "MgF.sub.2" or (magnesium near2 fluoride) or (magnesium near2 halide) or (metal near2 fluoride)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) and ((heater or susceptor or substrate or pedestal) with (polish\$4 or rough\$5 or smooth\$3 or 10RA or RA10) with (before or prior or previous\$2 or pretreat\$4 or (pre adj treat\$4)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3))	USPAT; US-PGPUB	2004/01/29 13:13
64	40	((heater or susceptor or pedestal) with (polish\$4 or rough\$5 or smooth\$3 or 10RA or RA10) with (before or prior or previous\$2 or pretreat\$4 or (pre adj treat\$4)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3))	USPAT; US-PGPUB	2004/01/29 13:20
65	586	((heater or susceptor or pedestal) with (polish\$4 or rough\$5 or smooth\$3 or 10RA or RA10) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3))	USPAT; US-PGPUB	2004/01/29 13:27
66	33	((heater or susceptor or pedestal) with (polish\$4 or rough\$5 or smooth\$3 or 10RA or RA10) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3)) and (((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.))	USPAT; US-PGPUB	2004/01/29 13:16

67	4	((heater or susceptor or pedestal) with (polish\$4 or smooth\$3) with (rough\$5 or 10RA or RA10) with (before or prior or previous\$2 or pretreat\$4 or (pre adj treat\$4)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3))	USPAT; US-PGPUB	2004/01/29 13:21
68	616	((polish\$4 or smooth\$3) with (rough\$5 or 10RA or RA10) with (before or prior or previous\$2 or pretreat\$4 or (pre adj treat\$4)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3))	USPAT; US-PGPUB	2004/01/29 13:27
69	21	(((polish\$4 or smooth\$3) with (rough\$5 or 10RA or RA10) with (before or prior or previous\$2 or pretreat\$4 or (pre adj treat\$4)) with (coat\$3 or film or layer or deposit\$3 or \$4CVD or apply\$3))) and (((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.))	USPAT; US-PGPUB	2004/01/29 13:21
70	12	((polish\$4 or smooth\$3) with (rough\$5 or 10RA or RA10) with (before or prior or previous\$2 or pretreat\$4 or (pre adj treat\$4)) with (\$4CVD or \$4PVD or EB or (electron adj beam)))	USPAT; US-PGPUB	2004/01/29 13:24
71	16	((polish\$4 or smooth\$3) with (rough\$5 or 10RA or RA10) with (before or prior or previous\$2 or pretreat\$4 or (pre adj treat\$4)) with (\$4CVD or \$4PVD or EB or (electron adj beam) or (vapor near2 deposit\$3)))	USPAT; US-PGPUB	2004/01/29 13:25
72	279	((polish\$4 or smooth\$3) with (before or prior or previous\$2 or pretreat\$4 or (pre adj treat\$4)) with (\$4CVD or \$4PVD or EB or (electron adj beam) or (vapor near2 deposit\$3)))	USPAT; US-PGPUB	2004/01/29 13:25
73	11	((polish\$4 or smooth\$3) with (before or prior or previous\$2 or pretreat\$4 or (pre adj treat\$4)) with (\$4CVD or \$4PVD or EB or (electron adj beam) or (vapor near2 deposit\$3)) with (benefi\$7 or advantag\$7 or optima\$7 or prefer\$6))	USPAT; US-PGPUB	2004/01/29 13:26
74	607	((heater or susceptor or pedestal or chuck or support) with (polish\$4 or smooth\$3) with (rough\$5 or 10RA or RA10))	USPAT; US-PGPUB	2004/01/29 13:31
75	15	(((heater or susceptor or pedestal or chuck or support) with (polish\$4 or smooth\$3) with (rough\$5 or 10RA or RA10))) and (((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.))	USPAT; US-PGPUB	2004/01/29 13:29
76	926	((heater or susceptor or pedestal or chuck or support) with (polish\$4 or smooth\$3) with (prefer\$6 or advantageous\$6 or benefi\$8 or desir\$6 or optim\$6))	USPAT; US-PGPUB	2004/01/29 13:36
77	8	(((heater or susceptor or pedestal or chuck or support) with (polish\$4 or smooth\$3) with (prefer\$6 or advantageous\$6 or benefi\$8 or desir\$6 or optim\$6))) and (((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.))	USPAT; US-PGPUB	2004/01/29 13:34
78	3	((heater or susceptor or pedestal or chuck or support) with (polish\$4 or smooth\$3) with (prefer\$6 or advantageous\$6 or benefi\$8 or desir\$6 or optim\$6) with (heat near2 transfer\$6))	USPAT; US-PGPUB	2004/01/29 13:38

80	1	((heater or susceptor or pedestal or chuck or support) with (polish\$4 or smooth\$3) with (heat near2 transfer\$6))) and (((427/585, 593, 596, 255.28, 255.39).CCLS.) ((427/372.2, 383.1).CCLS.) ((423/490, 497).CCLS.) ((118/715, 725, 728).CCLS.))	USPAT; US-PGPUB	2004/01/29 13:38
79	92	((heater or susceptor or pedestal or chuck or support) with (polish\$4 or smooth\$3) with (heat near2 transfer\$6))	USPAT; US-PGPUB	2004/01/29 13:57
81	9	((MgF2 or "MgF.sub.2" or (magnesium adj fluoride)) with (coat\$3 or film or layer) with (anneal\$5 or heat\$3) with (poros\$3 or void or dens\$9 or porous or nonporous or pack\$3))	USPAT; US-PGPUB	2004/01/29 14:00
82	158	((MgF2 or "MgF.sub.2" or (magnesium adj fluoride)) with (coat\$3 or film or layer) with (anneal\$5 or heat\$3))	USPAT; US-PGPUB	2004/01/29 14:07
83	149	((MgF2 or "MgF.sub.2" or (magnesium adj fluoride)) with (coat\$3 or film or layer) with (anneal\$5 or heat\$3))) not (((MgF2 or "MgF.sub.2" or (magnesium adj fluoride)) with (coat\$3 or film or layer) with (anneal\$5 or heat\$3) with (poros\$3 or void or dens\$9 or porous or nonporous or pack\$3)))	USPAT; US-PGPUB	2004/01/29 14:00
84	20	((MgF2 or "MgF.sub.2" or (magnesium adj fluoride)) with anneal\$4)	USPAT; US-PGPUB	2004/01/29 14:13
85	18	((MgF2 or "MgF.sub.2" or (magnesium adj fluoride)) with (heat\$3 near2 treat\$6))	USPAT; US-PGPUB	2004/01/29 14:10
86	4	((MgF2 or "MgF.sub.2" or (magnesium adj fluoride)) with anneal\$4)	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:11
87	16	((MgF2 or "MgF.sub.2" or (magnesium adj fluoride)) with (heat\$3 adj treat\$4))	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 14:12
88	17	((MgF2 or "MgF.sub.2" or (magnesium adj fluoride)) same (anneal\$4 or (heat\$3 adj treat\$5))) same (dens\$10 or void or hard\$5 or porous or nonporous or poros\$4 or pack\$5)	USPAT; US-PGPUB	2004/01/29 14:17
89	119	((fluoride) with (coat\$3 or film or layer) same (anneal\$4 or (heat\$3 adj treat\$5))) same (dens\$10 or void or hard\$5 or porous or nonporous or poros\$4 or pack\$5)	USPAT; US-PGPUB	2004/01/29 14:17
90	12	((fluoride) with (coat\$3 or film or layer) with (anneal\$4 or (heat\$3 adj treat\$5))) with (dens\$10 or void or hard\$5 or porous or nonporous or poros\$4 or pack\$5)	USPAT; US-PGPUB	2004/01/29 14:26
91	6688	((anneal\$4 or (heat\$3 adj treat\$5))) with (dens\$10 or void or hard\$5 or porous or nonporous or poros\$4 or pack\$5) with temperature	USPAT; US-PGPUB	2004/01/29 14:26
92	0	((anneal\$4 or (heat\$3 adj treat\$5))) with (dens\$10 or void or hard\$5 or porous or nonporous or poros\$4 or pack\$5) with temperature with (result near2 effective)	USPAT; US-PGPUB	2004/01/29 14:27
93	472	((anneal\$4 or (heat\$3 adj treat\$5))) with (dens\$10 or void or hard\$5 or porous or nonporous or poros\$4 or pack\$5) with temperature with (determin\$5 or depend\$5 or optim\$8 or routine or experiment\$6)	USPAT; US-PGPUB	2004/01/29 14:28

94	8	((anneal\$4 or (heat\$3 adj treat\$5))) with (dens\$10 or void or hard\$5 or porous or nonporous or poros\$4 or pack\$5) with temperature with (determin\$5 or depend\$5 or optim\$8 or routine or experiment\$6)) and (((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.))	USPAT; US-PGPUB	2004/01/29 14:28
95	2926	((anneal\$4 or (heat\$3 adj treat\$5))) with temperature with (determin\$5 or depend\$5 or optim\$8 or routine or experiment\$6) with time (((anneal\$4 or (heat\$3 adj treat\$5))) with temperature with (determin\$5 or depend\$5 or optim\$8 or routine or experiment\$6) with time) and (((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.))	USPAT; US-PGPUB	2004/01/29 14:31
96	46	(((anneal\$4 or (heat\$3 adj treat\$5))) with temperature with (determin\$5 or depend\$5 or optim\$8 or routine or experiment\$6) with time) and (((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.))	USPAT; US-PGPUB	2004/01/29 14:29
97	101	(((anneal\$4 or (heat\$3 adj treat\$5))) with temperature with time) and (((anneal\$4 or (heat\$3 adj treat\$5))) with temperature with time)) and (((427/372.2,383.1).CCLS.) and (((anneal\$4 or (heat\$3 adj treat\$5))) with temperature with time)) and (((427/585,593,596,255.28,255.39).CCLS.)	USPAT; US-PGPUB	2004/01/29 14:33
98	12	(((anneal\$4 or (heat\$3 adj treat\$5))) with temperature with (result near2 effective))	USPAT; US-PGPUB	2004/01/29 15:02
99	0	((MgF2 or (magnesium adj fluoride) or "MgF.sub.2") with (coat\$3 or film or layer or deposit\$3 or apply\$3 or \$4PVD or \$4CVD or EB or (electron adj beam))) and (temperature with ("250" or "300")) and ((vacuum or pressure) with ("-6"))	USPAT; US-PGPUB	2004/01/29 15:04
100	174	((MgF2 or (magnesium adj fluoride) or "MgF.sub.2") with (coat\$3 or film or layer or deposit\$3 or apply\$3 or \$4PVD or \$4CVD or EB or (electron adj beam))) and (temperature with ("250" or "300")) and ((vacuum or pressure or torr))	USPAT; US-PGPUB	2004/01/29 15:06
101	51	((MgF2 or (magnesium adj fluoride) or "MgF.sub.2") with (coat\$3 or film or layer or deposit\$3 or apply\$3 or \$4PVD or \$4CVD or EB or (electron adj beam))) and ((temperature with ("250" or "300")) same ((vacuum or pressure or torr)))	USPAT; US-PGPUB	2004/01/29 15:07
102	9	((MgF2 or (magnesium adj fluoride) or "MgF.sub.2") with (coat\$3 or film or layer or deposit\$3 or apply\$3 or \$4PVD or \$4CVD or EB or (electron adj beam))) and (temperature with ("250" or "300")) and ((vacuum or pressure or torr)) and (((427/585,593,596,255.28,255.39).CCLS.) ((427/372.2,383.1).CCLS.) ((423/490,497).CCLS.) ((118/715,725,728).CCLS.))	USPAT; US-PGPUB	2004/01/29 15:06
103	6	((MgF2 or (magnesium adj fluoride) or "MgF.sub.2") with (\$4PVD or \$4CVD or EB or (electron adj beam) or (vapor adj deposit\$4))).ti,ab.	USPAT; US-PGPUB	2004/01/29 15:15
104	131	((MgF2 or (magnesium adj fluoride) or "MgF.sub.2") with (\$4PVD or \$4CVD or EB or (electron adj beam) or (vapor adj deposit\$4)))	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 15:09
105	33	((MgF2 or (magnesium adj fluoride) or "MgF.sub.2") with (\$4PVD or \$4CVD or EB or (electron adj beam) or (vapor adj deposit\$4))) and ((temperature or temp\$10 or celcius or C or F or K or kelvin) and (pressure or vacuum or torr or pascal or atm or atmosphere))	EPO; JPO; DERWENT; IBM_TDB	2004/01/29 15:10

106	8	((MgF2 or (magnesium adj fluoride) or "MgF.sub.2") with (\$4PVD or \$4CVD or EB or (electron adj beam) or (vapor adj deposit\$4))) and (temperature near5 ("300" or "250")) and (pressure or vacuum)	USPAT; US-PGPUB	2004/01/29 15:15
-----	---	--	--------------------	------------------